ABSTRACT

PBGA SINGULATED SUBSTRATE FOR MODEL MELAMINE CLEANING

A new method is provided to clean melamine deposits from tools and components that are used to form molds around and to therewith encapsulate BGA devices. The cleaning process applies a dummy BGA substrate as part of and during the cleaning procedure. This dummy BGA substrate replaces the conventionally used copper strips that shield areas of the molding tools during the cleaning cycle. The dummy copper strips require, during and as part of the melamine cleaning process, frequent cleaning, which adds considerable to the time and expense of the melamine cleaning process. (Fig. 6)